

SEMI GLOBAL UPDATE

May 6, 2025

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What's New at SEMI



Conferences

SEMI 3D & Systems Summit to Spotlight Trends in Hybrid Bonding and Chiplet Architecture

"We look forward to welcoming industry leaders, innovators, and researchers to showcase their latest," said Laith Altimime, President of SEMI Europe.



Exhibitions and Conferences

SEMICON Europa 2025 Call for Abstracts Opens

Do you have an innovation or new development in advanced packaging or MEMS and sensors? Submit your abstract for SEMICON Europa 2025 by June 20.



Standards

SEMI Standards Q1 2025 Update: MEMS Manufacturing Readiness, Cybersecurity Initiatives, and More

SEMI Standards program made key progress in Q1 2025 to address increased cybersecurity threats and other challenges in microelectronics manufacturing.



Conference Takeaways

Europe's Semiconductor Strategy: Navigating Geopolitics, Building Resilience

During the SEMI ISS Europe, a high-level panel on the Geopolitics of Semiconductors brought together leaders from across the ecosystem to explore



Workforce Development

European Chips Skills Academy (ECSA) Skills Survey 2025

Help shape the ECSA Skills Strategy 2025 Report. Complete the survey by June 28 to identify skills gaps, workforce needs, and training priorities.



SEMI-Related

Semiecosystem: 5 Takeaways From Intel's Foundry Event

New processes, packages and alliances were among the hot topics

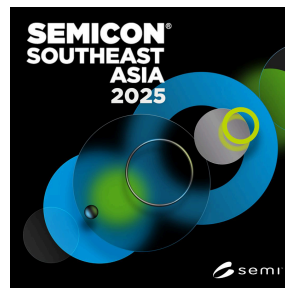
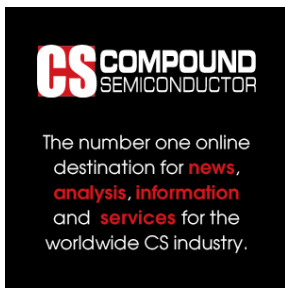
Upcoming Events/Webinars

May 7	Empowering Tomorrow's Precision MedTech With Sensor Solutions Virtual Pacific Time
May 8	Women in Semiconductors—WIS Albany, New York Eastern Time
May 15	Texas Spring Breakfast Forum Round Rock, Texas Central Time

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